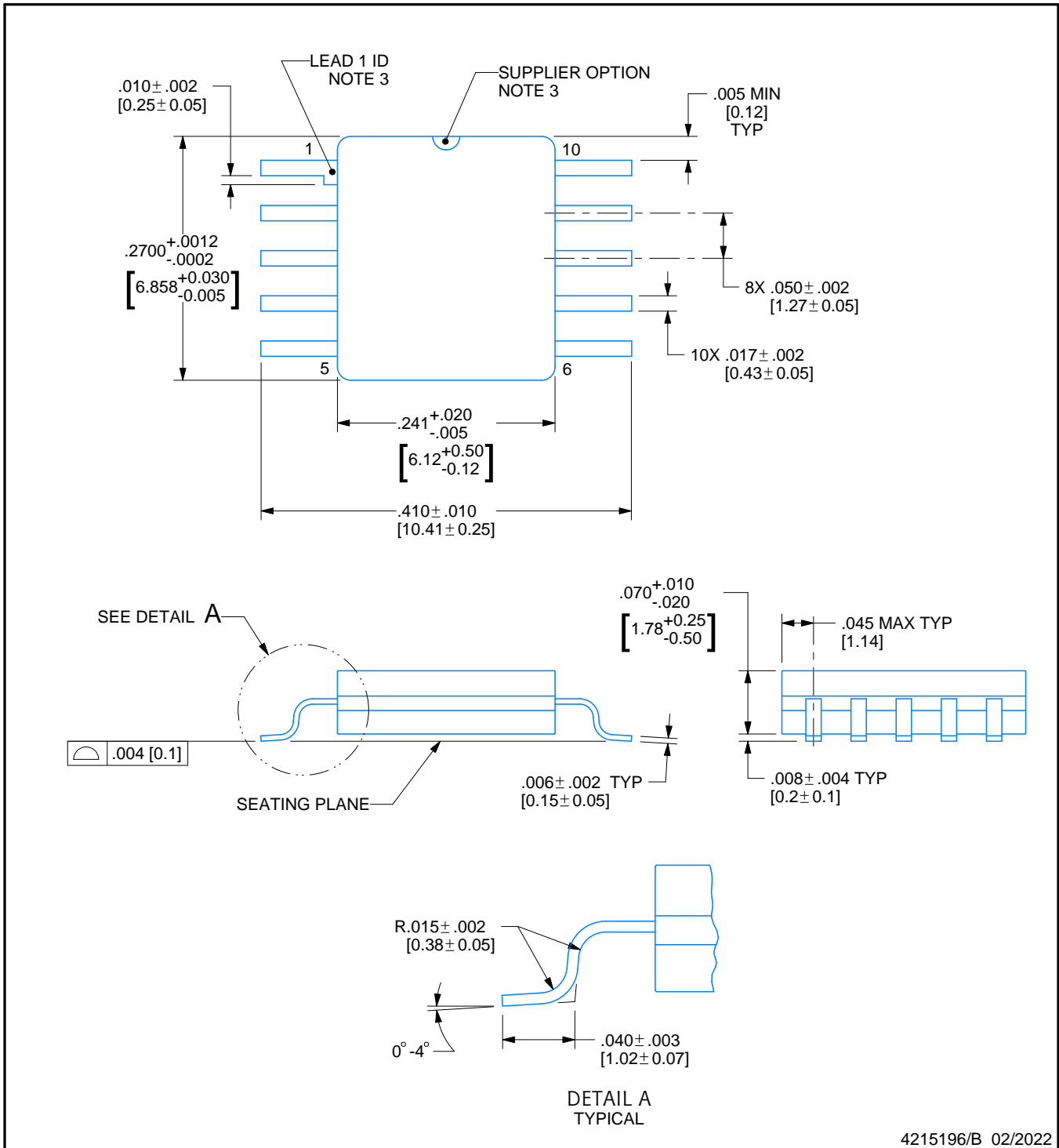


PACKAGE OUTLINE

NAC0010A

CFP - 2.33mm max height

CERAMIC FLATPACK



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NOTES:

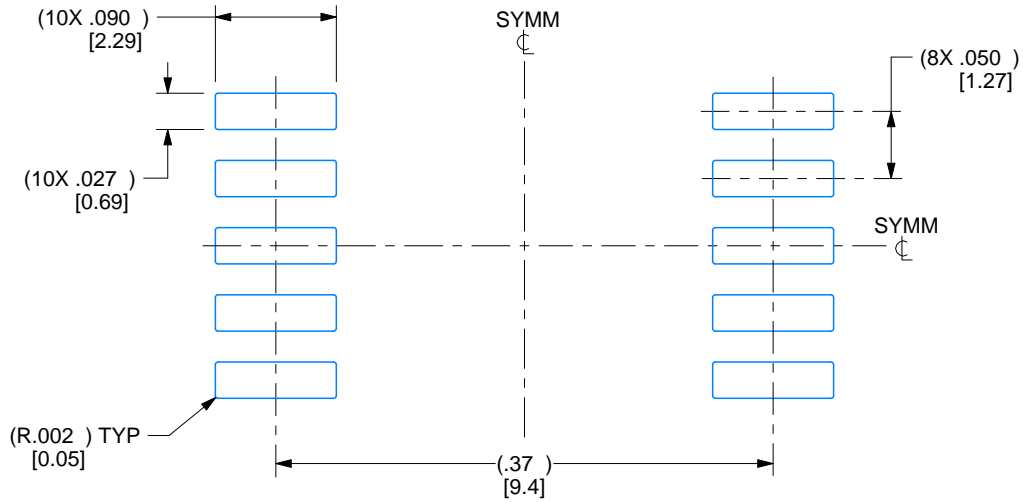
1. Controlling dimension is Inch. Values in [] are millimeters. Dimensions in () for reference only.
2. For solder thickness and composition, see the "Lead Finish Composition/Thickness" link in the packaging section of the Texas Instruments website
3. Lead 1 identification shall be:
 - a) A notch or other mark within this area
 - b) A tab on lead 1, either side
4. No JEDEC registration as of december 2021

EXAMPLE BOARD LAYOUT

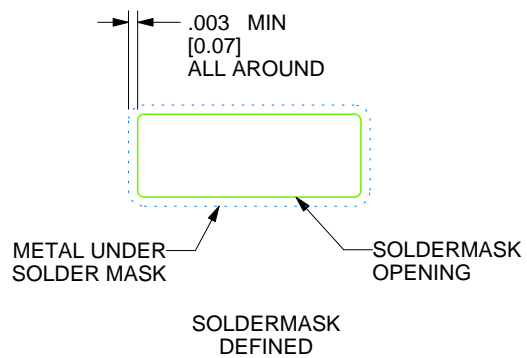
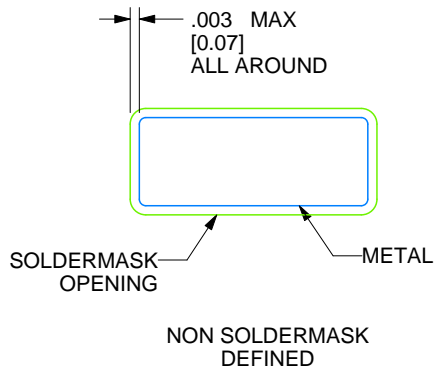
NAC0010A

CFP - 2.33mm max height

CERAMIC FLATPACK



RECOMMENDED LAND PATTERN



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